

# Complementary MOSFET Half-Bridge (N- and P-Channel)

## PRODUCT SUMMARY

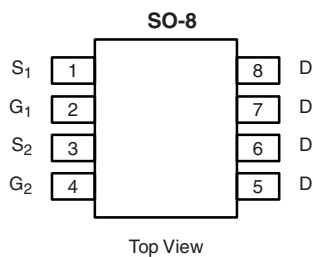
	$V_{DS}$ (V)	$R_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)
N-Channel	20	0.020 at $V_{GS} = 4.5$ V	9.1
		0.030 at $V_{GS} = 2.5$ V	7.5
P-Channel	- 20	0.060 at $V_{GS} = - 4.5$ V	- 5.3
		0.100 at $V_{GS} = - 2.5$ V	- 4.1

## FEATURES

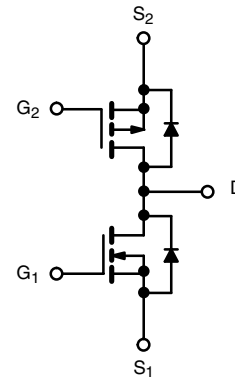
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Compliant to RoHS Directive 2002/95/EC



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
Available



**Ordering Information:** Si4500BDY-T1-E3 (Lead (Pb)-free)  
Si4500BDY-T1-GE3 (Lead (Pb)-free and Halogen-free)



## ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter		Symbol	N-Channel		P-Channel		Unit
			10 s	Steady State	10 s	Steady State	
Drain-Source Voltage		V <sub>DS</sub>	20		- 20		V
Gate-Source Voltage		V <sub>GS</sub>	± 12		± 12		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a,b</sup>	T <sub>A</sub> = 25 °C	I <sub>D</sub>	9.1	6.6	- 5.3	- 3.8	A
	T <sub>A</sub> = 70 °C		7.3	5.3	- 4.9	- 3.1	
Pulsed Drain Current		I <sub>DM</sub>	30		- 20		
Continuous Source Current (Diode Conduction) <sup>a,b</sup>		I <sub>S</sub>	2.1	1.1	- 2.1	- 1.1	
Maximum Power Dissipation <sup>a,b</sup>	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.5	1.3	2.5	1.3	W
	T <sub>A</sub> = 70 °C		1.6	0.8	1.6	0.8	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150				°C

## THERMAL RESISTANCE RATINGS

Parameter		Symbol	N-Channel		P-Channel		Unit
			Typ.	Max.	Typ.	Max.	
Maximum Junction-to-Ambient <sup>a</sup>	$t \leq 10$ s	$R_{thJA}$	40	50	41	50	°C/W
	Steady State		75	95	75	95	
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	20	22	23	26	

Notes:

a. Surface Mounted on FR4 board.

b.  $t \leq 10$  s.

SPECIFICATIONS T <sub>J</sub> = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions		Min.	Typ. <sup>a</sup>	Max.	Unit
Static							
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	N-Ch	0.6		1.5	V
		V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = - 250 μA	P-Ch	- 0.6		- 1.5	
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 12 V	N-Ch			± 100	nA
			P-Ch			± 100	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V	N-Ch			1	μA
		V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V	P-Ch			- 1	
		V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C	N-Ch			5	
		V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C	P-Ch			- 5	
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 4.5 V	N-Ch	30			A
		V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 4.5 V	P-Ch	- 20			
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 9.1 A	N-Ch		0.016	0.020	Ω
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 5.3 A	P-Ch		0.048	0.060	
		V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 3.3 A	N-Ch		0.024	0.030	
		V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 1 A	P-Ch		0.082	0.100	
Forward Transconductance <sup>b</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 9.1 A	N-Ch		29		S
		V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 5.3 A	P-Ch		11		
Diode Forward Voltage <sup>b</sup>	V <sub>SD</sub>	I <sub>S</sub> = 2.1 A, V <sub>GS</sub> = 0 V	N-Ch		0.8	1.2	V
		I <sub>S</sub> = - 2.1 A, V <sub>GS</sub> = 0 V	P-Ch		- 0.8	- 1.2	
Dynamic <sup>a</sup>							
Total Gate Charge	Q <sub>g</sub>	N-Channel V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 9.1 A	N-Ch		11	17	nC
Gate-Source Charge	Q <sub>gs</sub>		P-Ch		6.0	9	
		Gate-Drain Charge	Q <sub>gd</sub>	P-Channel V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 5.3 A	N-Ch		
P-Ch					1.3		
Turn-On Delay Time	t <sub>d(on)</sub>	N-Channel V <sub>DD</sub> = 10 V, R <sub>L</sub> = 10 Ω I <sub>D</sub> ≅ 1 A, V <sub>GEN</sub> = 10 V, R <sub>g</sub> = 6 Ω	N-Ch		35	50	ns
			P-Ch		20	30	
Rise Time	t <sub>r</sub>		N-Ch		50	80	
			P-Ch		35	60	
Turn-Off Delay Time	t <sub>d(off)</sub>	P-Channel V <sub>DD</sub> = - 10 V, R <sub>L</sub> = 10 Ω I <sub>D</sub> ≅ - 1 A, V <sub>GEN</sub> = - 4.5 V, R <sub>g</sub> = 6 Ω	N-Ch		31	50	
			P-Ch		55	85	
Fall Time	t <sub>f</sub>		N-Ch		15	30	
			P-Ch		35	60	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 2.1 A, dI/dt = 100 A/μs	N-Ch		30	60	
		I <sub>F</sub> = - 2.1 A, dI/dt = 100 A/μs	P-Ch		25	50	

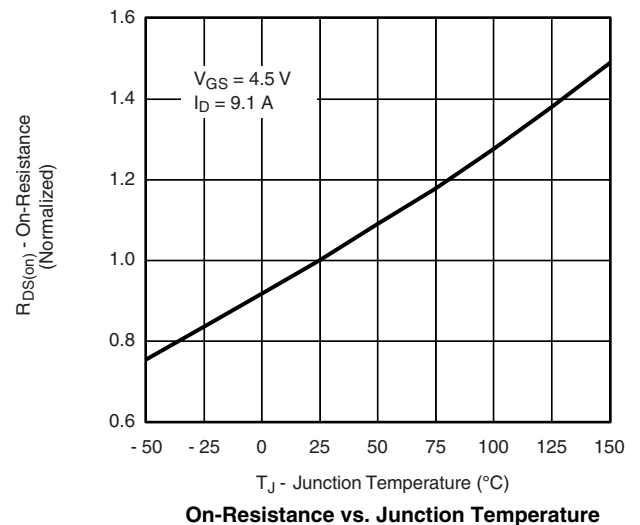
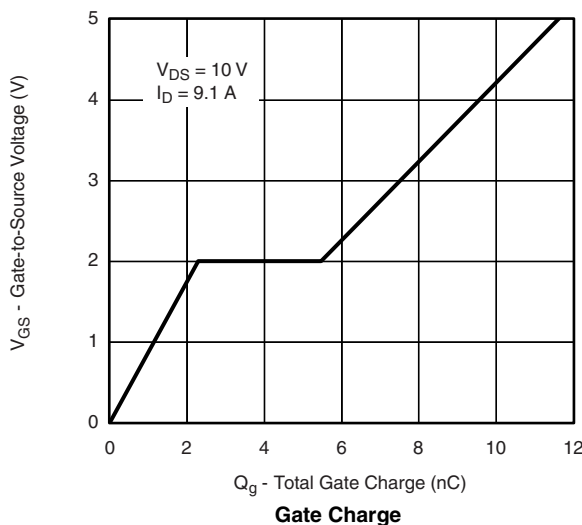
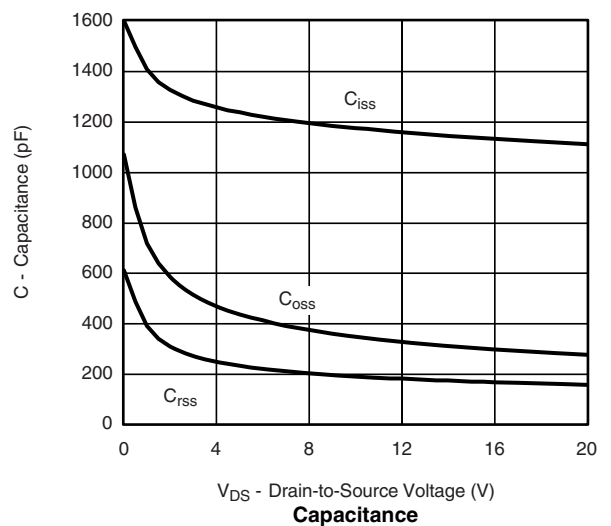
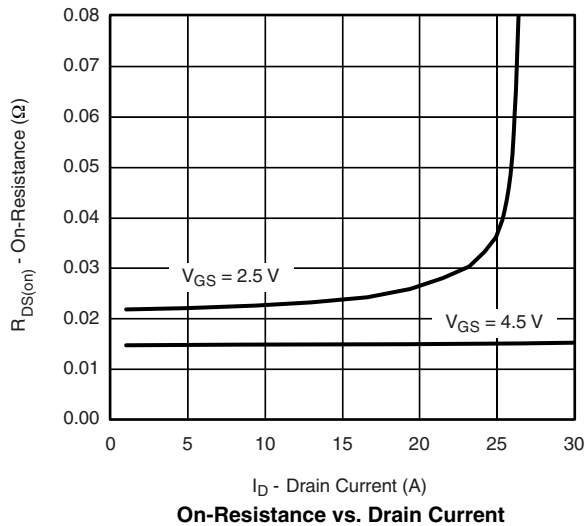
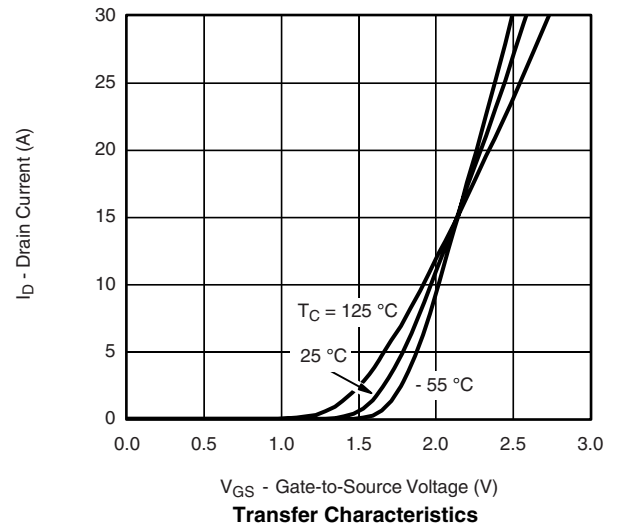
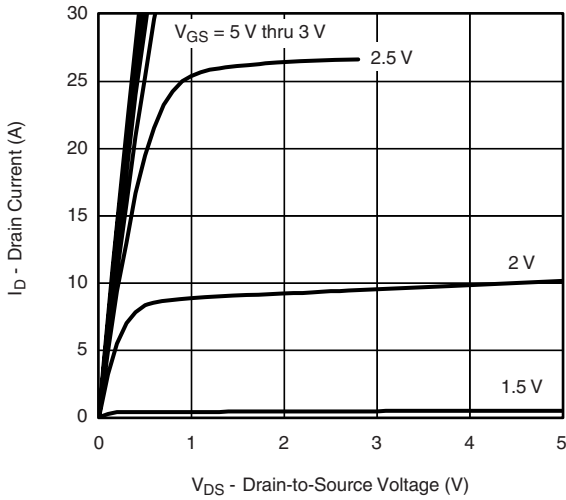
Notes:

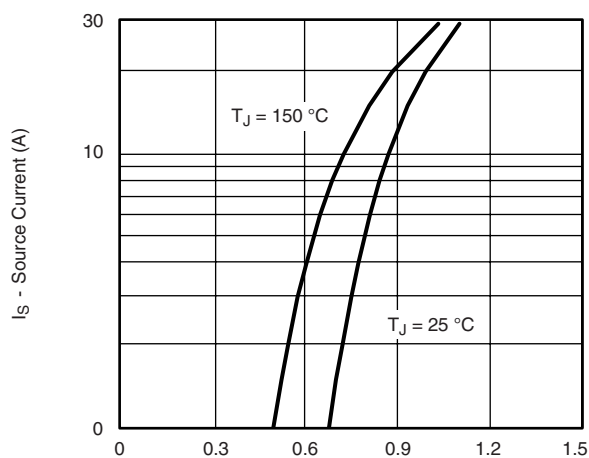
a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .

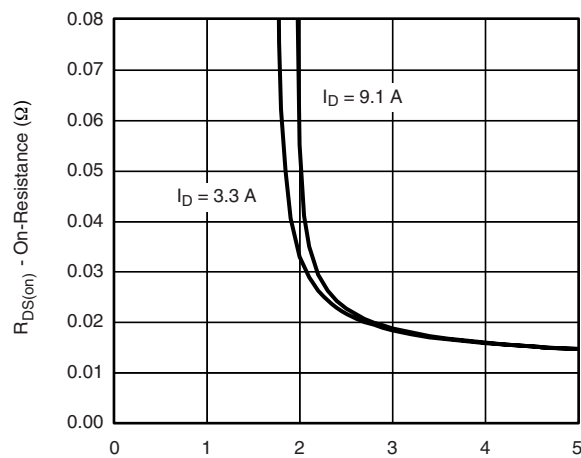
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

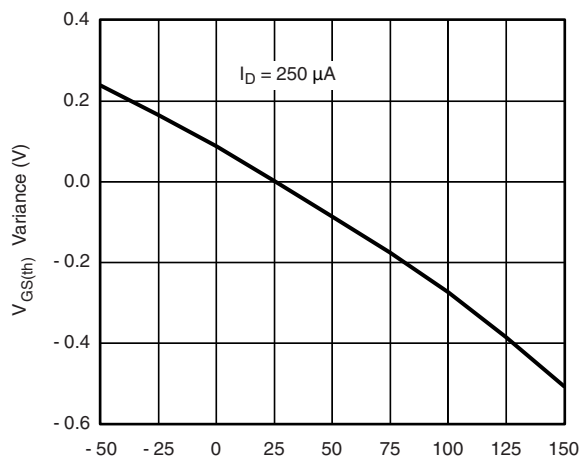


**N-CHANNEL TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted

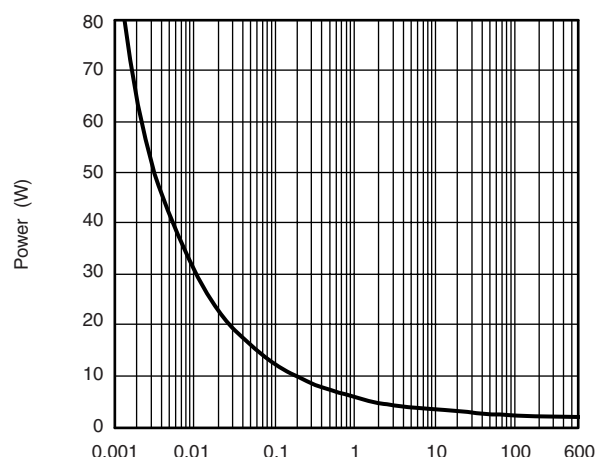
$V_{SD}$  - Source-to-Drain Voltage (V)  
Source-Drain Diode Forward Voltage



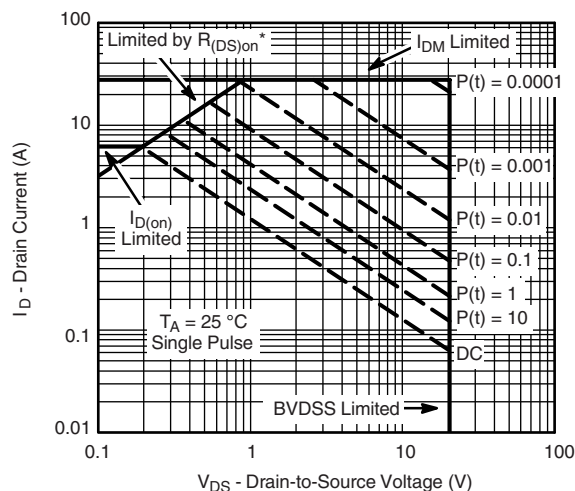
$V_{GS}$  - Gate-to-Source Voltage (V)  
On-Resistance vs. Gate-to-Source Voltage



$T_J$  - Temperature ( $^{\circ}\text{C}$ )  
Threshold Voltage



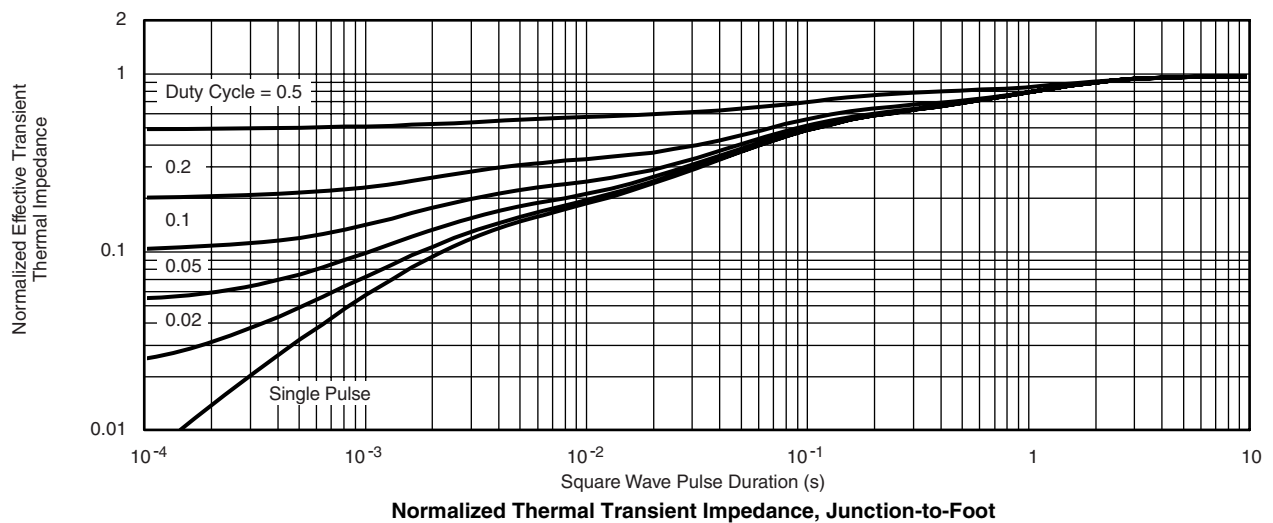
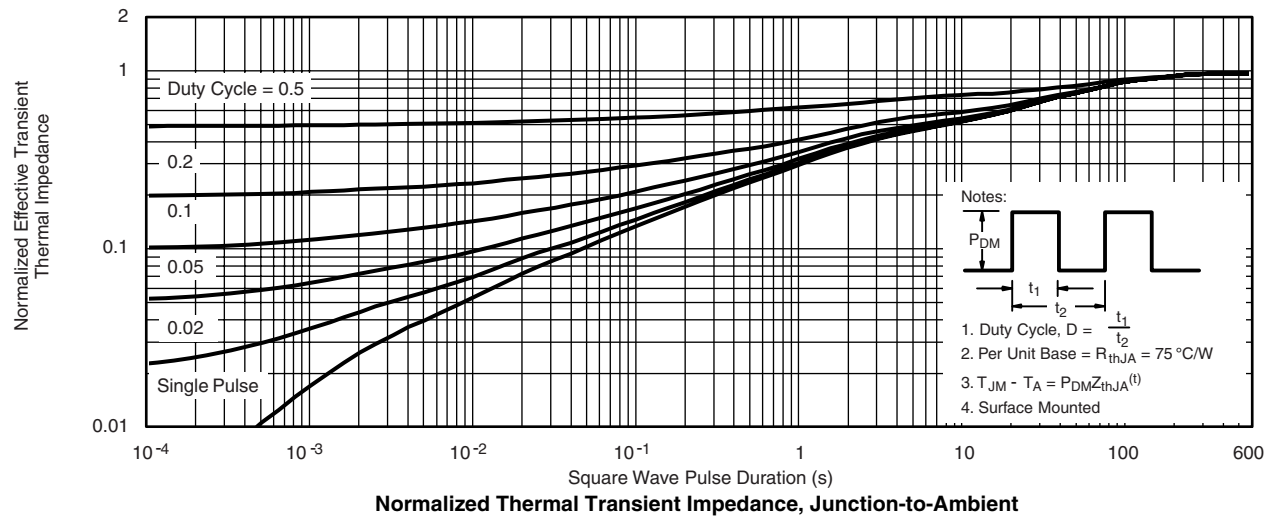
Single Pulse Power

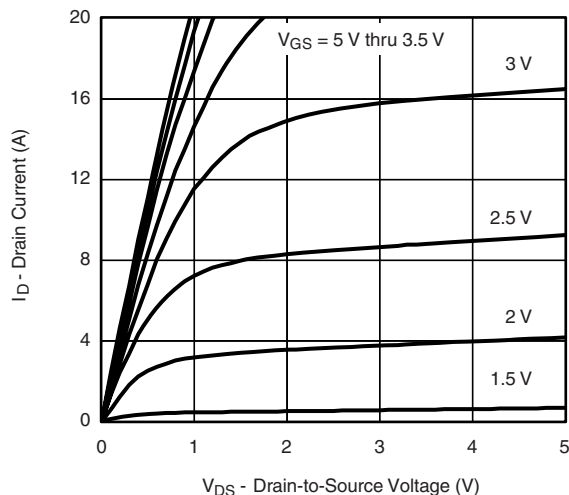
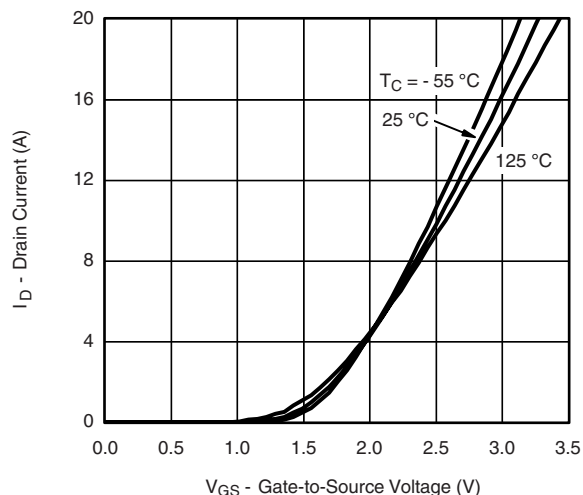
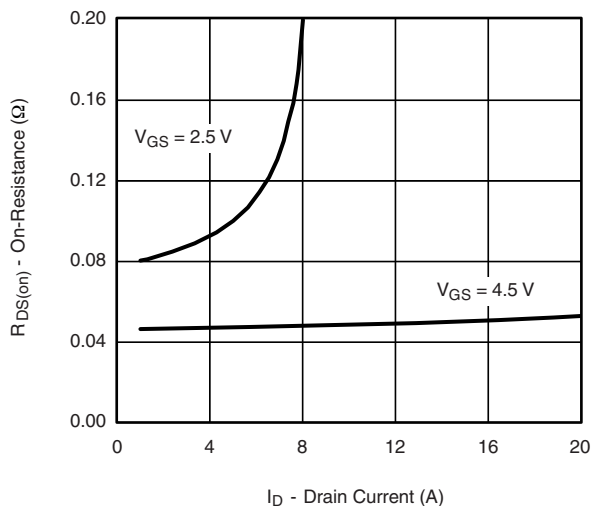
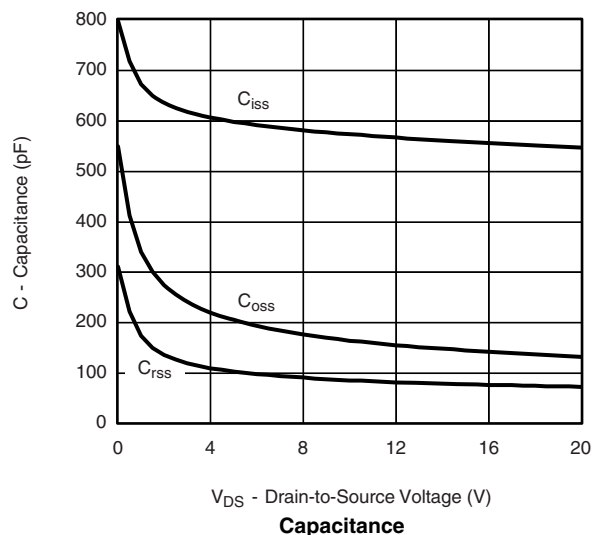
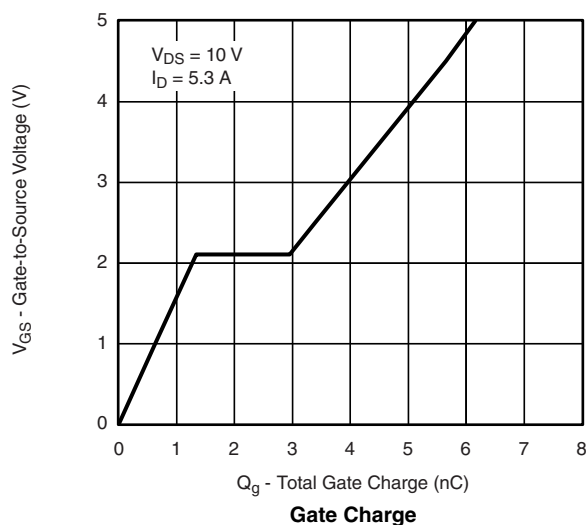
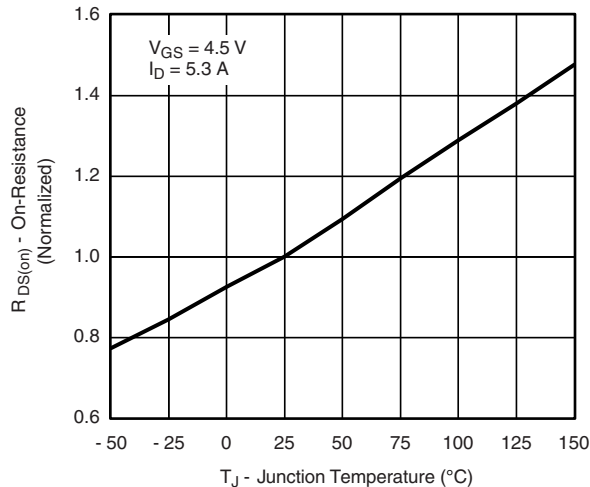


\*  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

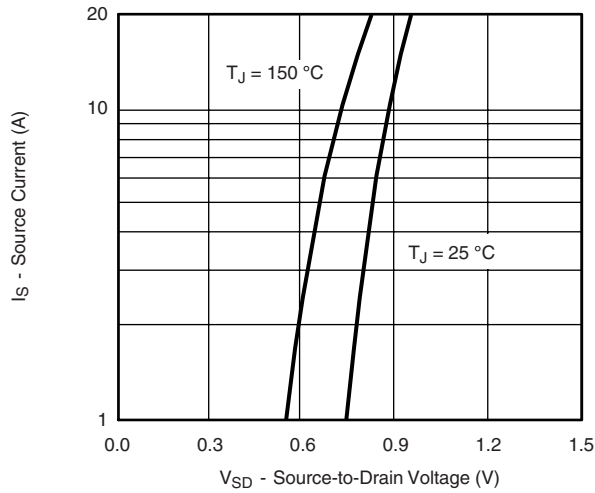
Safe Operating Area

## N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

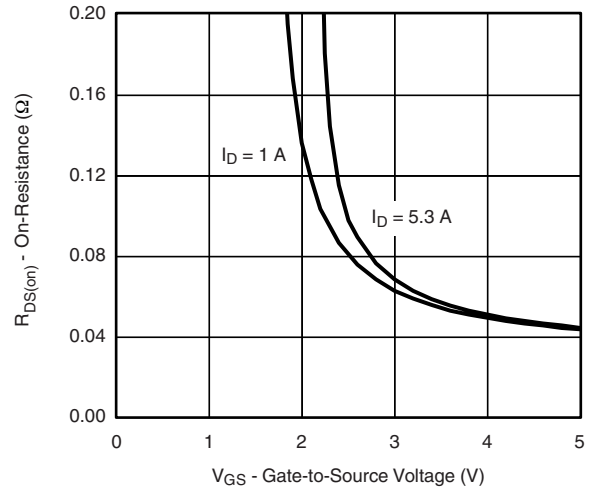


**P-CHANNEL TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted**Output Characteristics****Transfer Characteristics****On-Resistance vs. Drain Current****Capacitance****Gate Charge****On-Resistance vs. Junction Temperature**

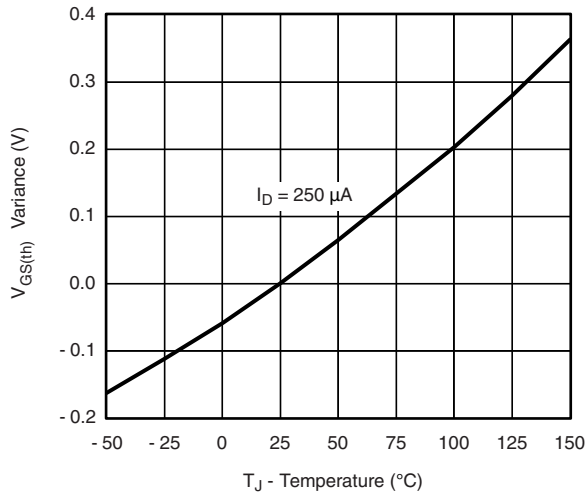
## P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



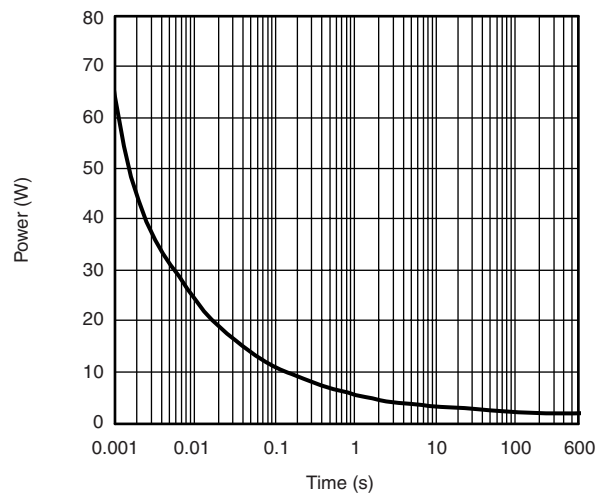
Source-Drain Diode Forward Voltage



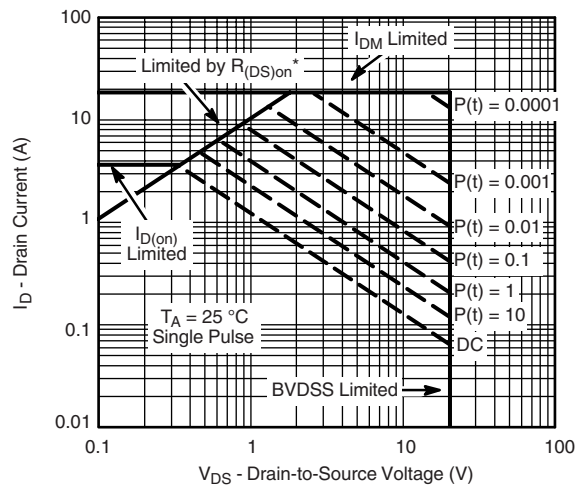
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

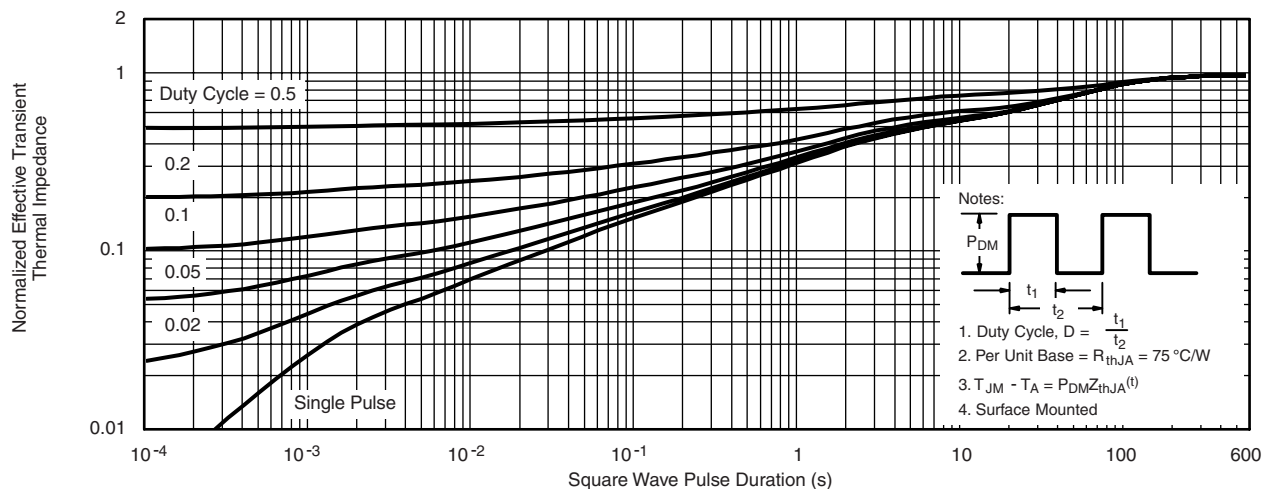
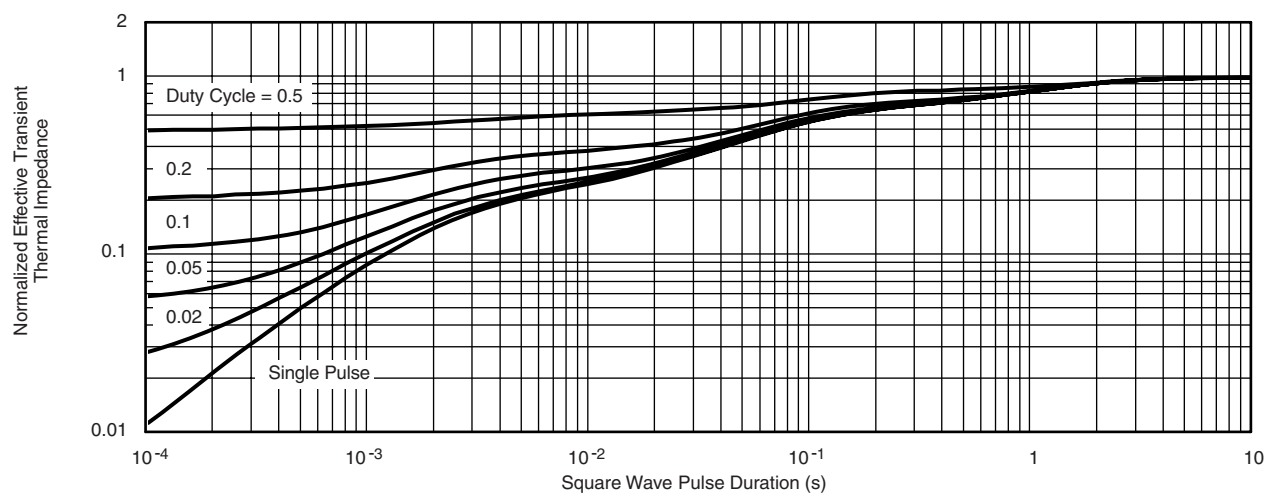


Single Pulse Power



\*  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area

**P-CHANNEL TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted**Normalized Thermal Transient Impedance, Junction-to-Ambient****Normalized Thermal Transient Impedance, Junction-to-Foot**

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